



DOCUMENT CHANGE REQUEST

DCR number 1219 Changes required for: General

Originator: Steve Jeffery

Date: 2019/06/28

Date sent: 2019/01/22

Organisation: ESCC Executive

Status: IMPLEMENTED

Title: Generic Specification for Discrete Semiconductor Components

Number: 5000

Issue: 7

Other documents affected:

Page:

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Paragraph:

8.24 TERMINAL STRENGTH

Original wording:

See the relevant paragraph of ESCC 5000 Issue 7.

Proposed wording:

- Add a new initial sentence Unless otherwise specified the following Terminal Strength test conditions shall apply: followed by a line space.
- Amend ...chip carrier packages. to ...chip carrier packages, surface mount packages and similar package types.

Justification:

The editorial-only changes proposed above are based on a valid request (to introduce Surface Mount Package with the chip carrier package in Para. 8.24, the Terminal Strength requirements paragraph) from qualified manufacturer ST.

ST have also recently confirmed that all their components packaged in Surface Mount packages such as SMD.5, SMD1 and SMD2 are actually subjected to the Terminal Strength test which is currently defined in ESCC 5000 only for chip carrier packages.

These changes therefore improve the spec by removing any ambiguity regarding the applicability of the Terminal Strength test for the Surface Mount packaged components which are currently specified in a number of ESCC Detail Specs.

Attachments:
N/A
Modifications:
N/A
Approval signature:

Date signed:
2019-06-28